

General purpose SCR suited for power supplies up to 400 Hz on resistive or inductive loads.

- $V_{DRM} = V_{RRM}$ up to 800 V.
- Glass passivated chip - High stability and reliability.
- High surge capability.

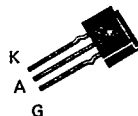
Thyristors à usage général pour des alimentations jusqu'à 400 Hz sur charges résistives ou inductives.

- $V_{DRM} = V_{RRM}$ jusqu'à 800 V.
- Pastille glassivée - Grande stabilité des caractéristiques.
- Courant de surcharge élevé.

$$I_T(RMS) = 1,6 \text{ A} / T_L = 50^\circ\text{C}$$

$$100 \text{ V} < \frac{V_{DRM}}{V_{RRM}} < 800 \text{ V}$$

Case : TL (CB-274) plastic
Boîtier :



ABSOLUTE RATINGS (LIMITING VALUES) VALEURS LIMITES ABSOLUES D'UTILISATION

	Symbol	Value	Unit
RMS on-state current* <i>Courant efficace à l'état passant*</i>	$I_T(RMS)$	1,6 @ $T_L = 50^\circ\text{C}$	A
Mean on-state current* <i>Courant moyen à l'état passant*</i>	$I_T(AV)$	1 @ $T_L = 50^\circ\text{C}$	A
Non repetitive surge peak on-state current** <i>Courant non répétitif de surcharge crête accidentelle à l'état passant**</i>	I_{TSM} I_{TSM}	73 (t = 8,3 ms) 70 (t = 10 ms) @ $T_J \leq 110^\circ\text{C}$	A A
I_2t for fusing <i>Valeur de la constante I_2t</i>	I_2t	25 (t = 10 ms) @ $T_J \leq 110^\circ\text{C}$	A ² s
Critical rate of rise of on-state current*** <i>Vitesse critique de croissance du courant à l'état passant***</i>	di/dt	100	A/μs
Storage and operating junction temperatures <i>Températures extrêmes de stockage et de jonction en fonctionnement</i>	T_{stg} T_J	- 40, + 150 - 40, + 110	°C °C

@ $T_J = 110^\circ\text{C}$	TL 1003	TL 2003	TL 4003	TL 6003	TL 8003
$V_{DRM} = V_{RRM}$ (V)	100	200	400	600	800

Thermal resistances <i>Résistances thermiques</i>	Symbol	Value	Unit
— Junction-leads <i>Jonction-connexions</i>	$R_{th(j-l)}$	35	°C/W
— Junction-ambient on printed circuit (with Cu 1 cm ²) <i>Jonction-ambiante sur circuit imprimé (avec Cu 1 cm²)</i>	$R_{th(j-a)}$	50	°C/W

*Single phase circuit, 180° conduction angle
*Circuit monophasé, angle de conduction 180°

*** $I_{GT} = 100 \text{ mA}$ di/dt = 1 A/μs

**Half-sine wave
**Demi-onde sinusoïdale

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May 1984 - 1/4

GATE CHARACTERISTICS (Maximum values)
CARACTERISTIQUES DE GACHETTE (Valeurs maximales)
PGM = 20 W ($t = 10 \mu\text{s}$)IFGM = 1 A ($t = 10 \mu\text{s}$)

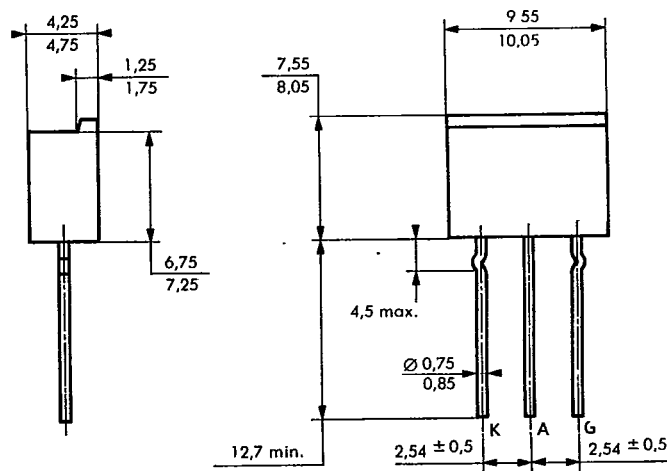
VRGM = 5 V

PG(AV) = 0,1 W

VFGM = 15 V ($t = 10 \mu\text{s}$)
ELECTRICAL CHARACTERISTICS
CARACTERISTIQUES ELECTRIQUES

Symbol	Value			Unit	Test conditions			
	min	typ	max					
I_{GT}			15	mA	$T_J = 25^\circ\text{C}$	$V_D = 12 \text{ V}$	$R_L = 33 \Omega$	$t_p \geq 20 \mu\text{s}$
V_{GT}		1,2	3	V	$T_J = 25^\circ\text{C}$	$V_D = 12 \text{ V}$	$R_L = 33 \Omega$	$t_p \geq 20 \mu\text{s}$
V_{GD}	0,2			V	$T_J = 110^\circ\text{C}$	$V_D = V_{DRM}$	$R_L = 3,3 \text{ k}\Omega$	
I_H		20		mA	$T_J = 25^\circ\text{C}$	$I_T = 100 \text{ mA}$	Gate open	
V_{TM}			1,8	V	$T_J = 25^\circ\text{C}$	$I_{TM} = 3,2 \text{ A}$	$t_p = 10 \text{ ms}$	
I_{DRM}			2	mA	$T_J = 110^\circ\text{C}$	V_{DRM} specified		
I_{RRM}			2	mA	$T_J = 110^\circ\text{C}$	V_{RRM} specified		
t_{gt}		1,5		μs	$T_J = 25^\circ\text{C}$ $I_G = 100 \text{ mA}$	$I_T = 3,2 \text{ A}$ $di_g/dt = 1 \text{ A}/\mu\text{s}$	$V_D = V_{DRM}$	
t_q		80		μs	$T_J = 110^\circ\text{C}$ $di_R/dt = 10 \text{ A}/\mu\text{s}$	$I_T = 1 \text{ A}$ $dv/dt = 20 \text{ V}/\mu\text{s}$	$V_R = 10 \text{ V}$ $V_D = 0,67 V_{DRM}$ Gate open	
dv/dt^*		100		V/ μs	$T_J = 110^\circ\text{C}$	Linear slope up to 0,67 V_{DRM} specified Gate open		

*For higher guaranteed values, please consult us.

CASE DESCRIPTION
DESCRIPTION DU BOITIER


TL (CB-274) plastic

 Cooling method : by convection (method A)
 Marking : type number
 Weight : 0,8 g

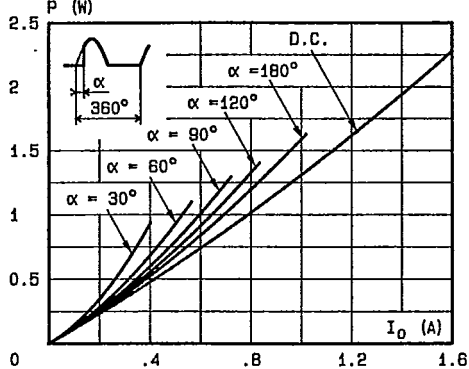


Fig.1 - Maximum mean power dissipation - versus mean on-state current.

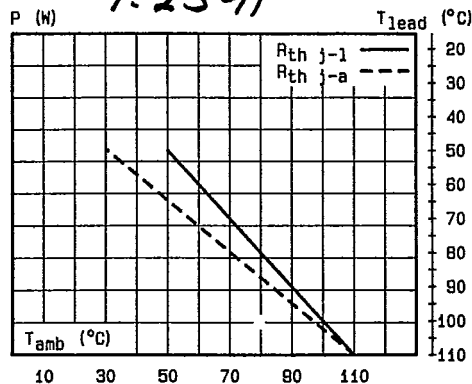


Fig.2 - Correlation between maximum mean power dissipation and maximum allowable temperatures (T_{amb} and T_{lead}).

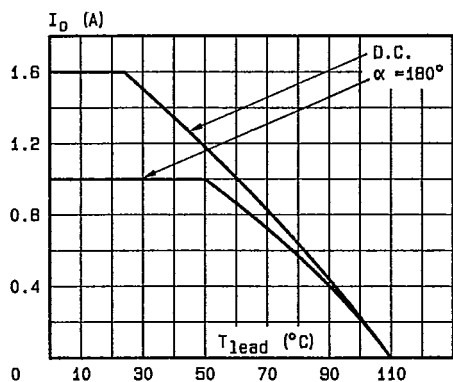


Fig.3 - Mean on-state current versus leads temperature.

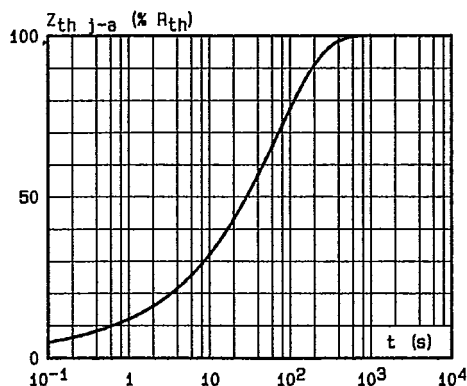


Fig.4 - Thermal transient impedance junction to ambient versus pulse duration.

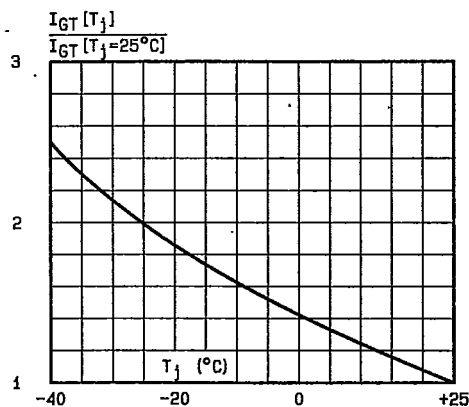


Fig.5 - Relative variation of gate trigger current versus junction temperature.

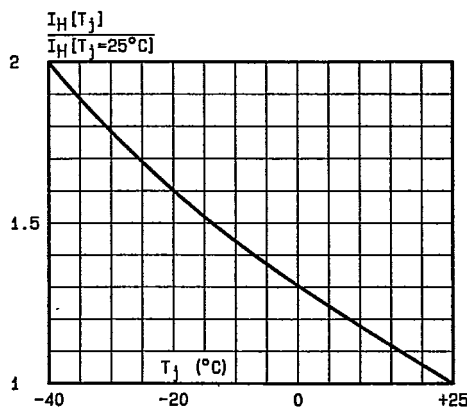


Fig.6 - Relative variation of holding current versus junction temperature.

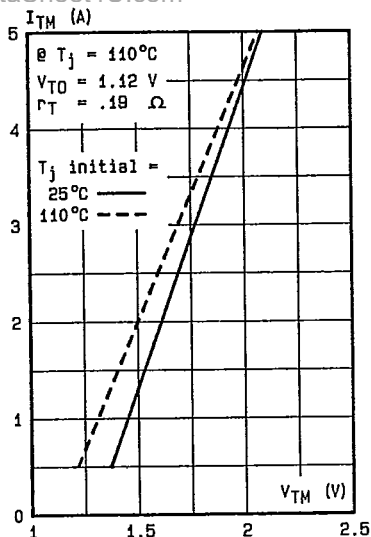


Fig.7 - On-state characteristics at low level (maximum values).

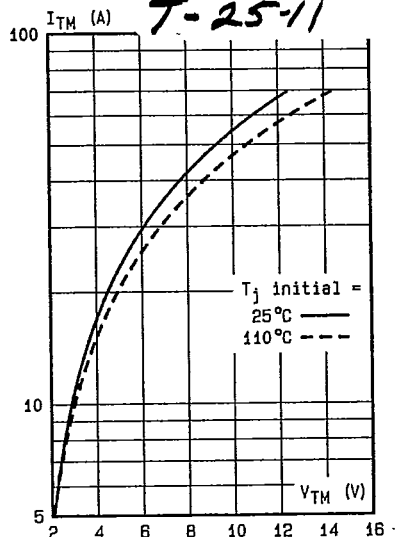


Fig.8 - On-state characteristics at high level (maximum values).

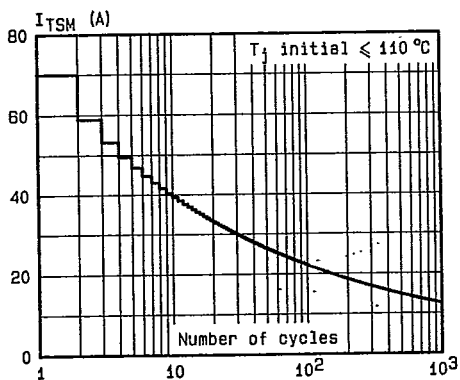


Fig.9 - Non repetitive surge peak on-state current versus number of cycles.

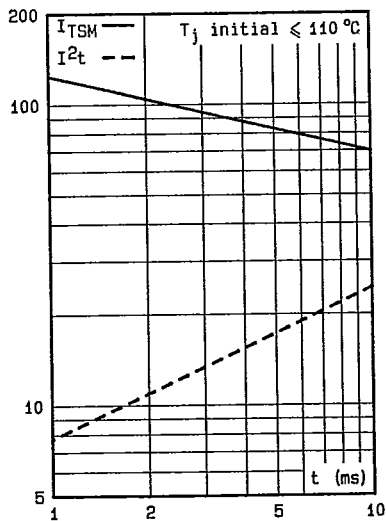


Fig.10 - Non repetitive surge peak on-state current for a sinusoidal pulse with width: $t \leq 10 \text{ ms}$ and corresponding value of I^2t .